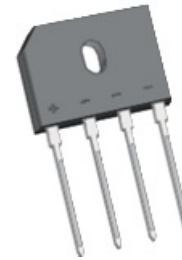


20A Single Phase Bridge Rectifier

Features

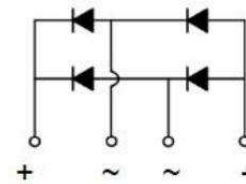
- Ideal for printed circuit boards
- High case dielectric strength
- Reverse Voltage : 50 to 1000V
- Forward Current : 20A
- High temperature soldering : 260°C/10s at terminals



GBU

Applications

- General purpose use in AC/DC bridge full wave rectification for printer, power supply, switching mode power supply, adapter, and home appliances applications.



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbol	GBU 20005	GBU 2001	GBU 2002	GBU 2004	GBU 2006	GBU 2008	GBU 2010	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ $T_C=100^\circ\text{C}$ with heatsink (Note 1)	$I_{F(AV)}$	20							A
Peak Forward Surge Current 8.3mS single half sine wave superimposed on rated load(JEDEC method)	I_{FSM}	240							A
Rating for fusing ($t < 8.3\text{ms}, T_j = 25^\circ\text{C}$)	I^2t	239							A^2s
Maximum Instantaneous Forward Voltage @10A	V_F	1.0							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_A=25^\circ\text{C}$	10							μA
	$T_A=125^\circ\text{C}$	500							
Typical Thermal Resistance (Note 1)	$R_{\theta JC}$	1.6							$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	(-55 to +150)							$^\circ\text{C}$

Notes:

1. Device mounted on 75mm*75mm*1.6mm Al plate heatsink.

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

FIG.1 - Typical forward current derating curve

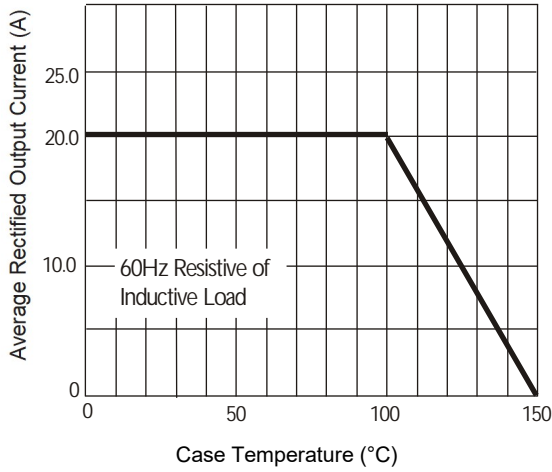


FIG.2 - Maximum Non-Repetitive Peak Forward Surge Current

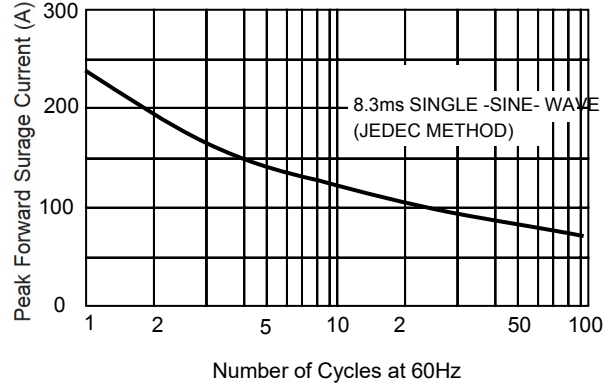


FIG.3 - Typical Junction Capacitance

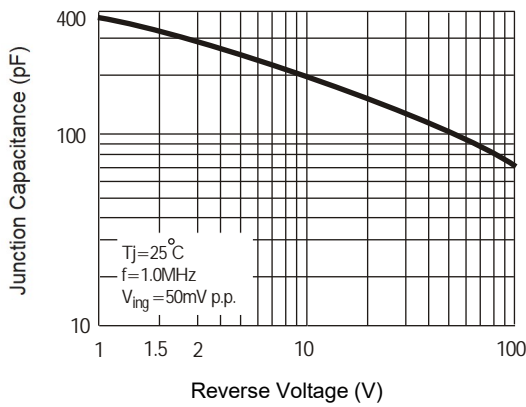


FIG.4 - Typical Instantaneous Forward Characteristics

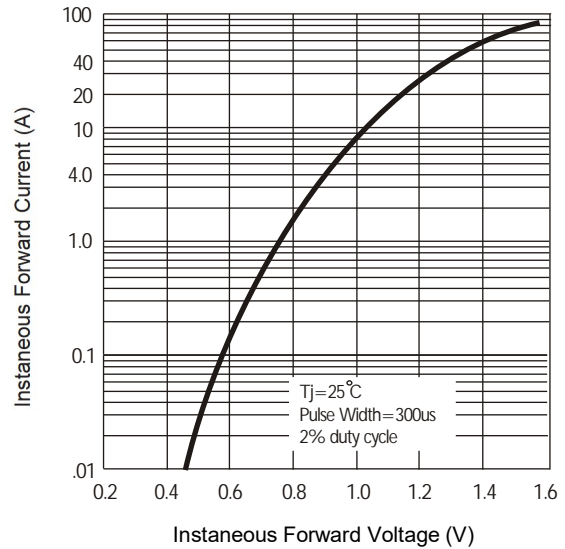
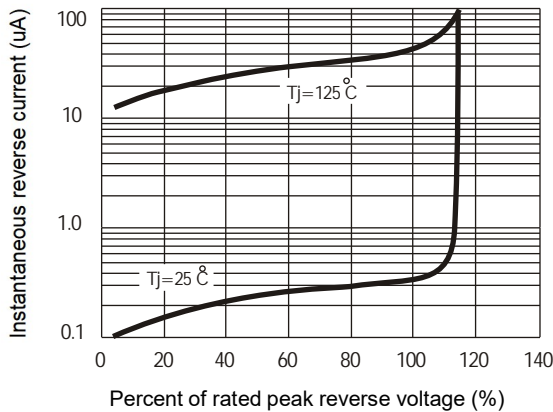
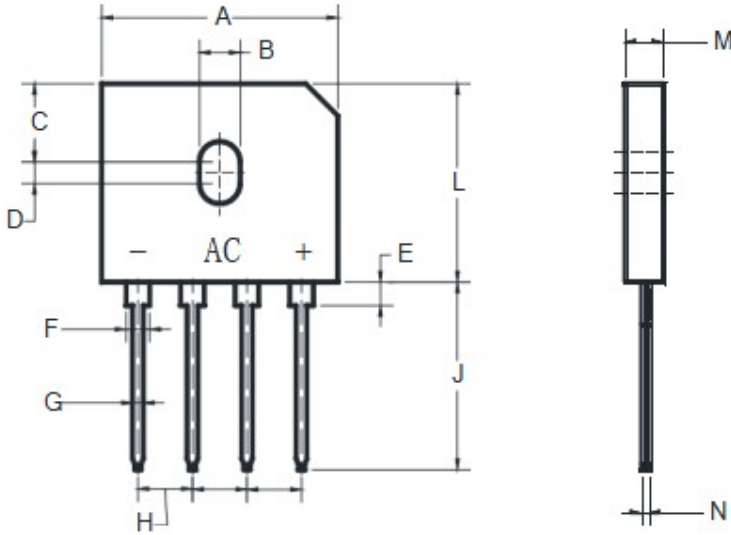


FIG.5 - Typical reverse Characteristics



Package Outlines (Dimensions in mm)

Plastic surface mounted package(GBU)



GBU		
Dim	Min	Max
A	21.70	22.50
B	3.40	4.10
C	7.40	8.00
D	1.65	2.26
E	2.25	2.85
F	2.05	2.4
G	1.02	1.37
H	4.83	5.43
J	17.0	18.6
L	18.3	18.9
M	3.30	3.66
N	0.46	0.66

Dimensions in millimeters

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